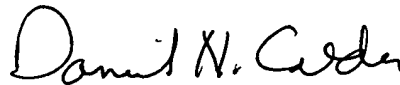


REMARKS

This is a divisional application of patent application Serial Number 08/815,656. The title and the specification have been amended. Claims 1-10 have been cancelled. Claims 11-19 remain and these claims are presented for examination.

Respectfully submitted,

RATNER & PRESTIA



Daniel N. Calder, Reg. No. 27,424
Attorney for Applicants

DNC/pb

Attachment: Version with Markings to Show Changes Made

Dated: November 2, 2001

Suite 301

One Westlakes, Berwyn

P.O. Box 980

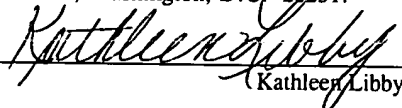
Valley Forge, PA 19482-0980

(610) 407-0700

The Assistant Commissioner for Patents is hereby authorized to charge payment to Deposit Account No. 09-0457 (IBM Corporation) of any fees associated with this communication.

EXPRESS MAIL Mailing Label Number: EL 910363993 US
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I hereby certify that this paper and fee is being deposited, under 37 C.F.R. § 1.10 and with sufficient postage, using the "Express Mail Post Office to Addressee" service of the United States Postal Service on the date indicated above and that the deposit is addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.


Kathleen Libby

10001424-110201

VERSION WITH MARKINGS TO SHOW CHANGES MADEIN THE TITLE:

[PROCESS TO PRODUCE A HIGH TEMPERATURE
INTERCONNECTION] LOW TEMPERATURE SOLDER CHIP ATTACH
STRUCTURE.

IN THE SPECIFICATION:

Insert before the first line of the specification --This application
is a divisional of U.S. Patent Application Serial Number 08/815,656, filed on
March 13, 1997, which has been allowed.--

IN THE CLAIMS:

Claims 1-10 have been cancelled.

10001421-110201